Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-10-10
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	MDG MD CHAMPION	Representative Title	MDG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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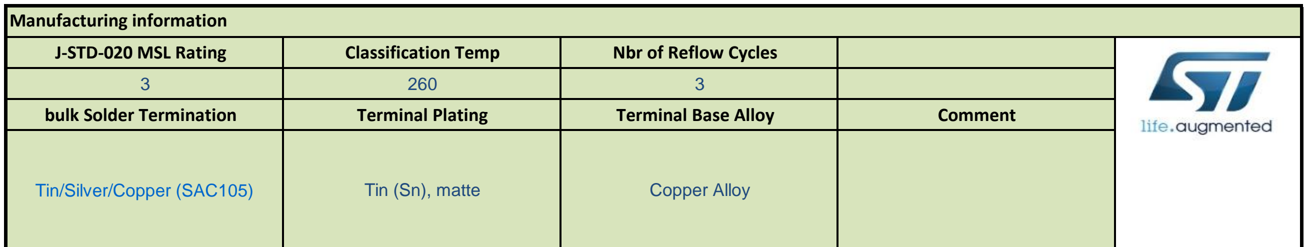
Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier’s liability and the Company’s remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	**Mfr Item Name**	**Version**	**Mfr Site**	**Date**
STM32F765NIH6	46RM*451XXXZ	A	9996	2017-10-10
	Amount	UoM	**Unit type**	**ST ECOPACK Grade**
	358.31	mg	Each	ECOPACK® 2
.	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		



Manufacturing information				
J-STD-020 MSL Rating	**Classification Temp**	**Nbr of Reflow Cycles**		life.augmented
3	260	3		
bulk Solder Termination	**Terminal Plating**	**Terminal Base Alloy**	**Comment**	
Tin/Silver/Copper (SAC105)	Tin (Sn), matte	Copper Alloy		

Package Designator	**Size**	**Nbr of instances**	**Shape**	
BGA	13,13,1.2	216	No lead	
Comment	Package : A0L2 TFBGA 13X13X1.2 216L P 0.8 MM 8373526			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	**Response**
1 - Product(s) meets EU RoHS requirement without any exemptions	**TRUE**
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE

Exemption Id.	Description

QueryList : REACH- 7th July 2017	
Query	**Response**
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH	**TRUE**

CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						**Mfr Item Name**	**46RM*451XXXZ**				7000001.0	1000000.0
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die or dies	M-011 Other inorganic materials	15.907	mg	supplier	die	Silicon (Si)	7440-21-3		14.325	mg	900547	39979
				supplier	metallization	Aluminium (Al)	7429-90-5		0.111	mg	6978	310
				supplier	metallization	Copper (Cu)	7440-50-8		0.719	mg	45200	2007
				supplier	metallization	Cobalt (Co)	7440-48-4		0.002	mg	126	6
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.100	mg	6287	279
				supplier	metallization	Tungsten (W)	7440-33-7		0.323	mg	20306	901
				supplier	Passivation	Silicon Nitride	12033-89-5		0.084	mg	5281	234
				supplier	Passivation	Silicon Oxide	7631-86-9		0.243	mg	15276	678
SILICON DIE	M-011 Other inorganic materials	14.325	mg	supplier	DIE	Silicon (Si)	7440-21-3		14.325	mg	1000000	39980
SUBSTRATE (DS7409HGB)	M-011 Other inorganic materials	112.657	mg	supplier	CORE	Glass Cloth	65997-17-3		19.152	mg	170000	53450
				supplier	CORE	Epoxy resin	61788-97-4		4.506	mg	40000	12576
				supplier	CORE	Flame resistant epoxy resin	223769-10-6		4.506	mg	40000	12576
				supplier	CORE	Heat resistant resin	25722-66-1		4.506	mg	40000	12576
				supplier	CORE	Silica filler	7631-86-9		12.392	mg	110000	34585
				supplier	CORE	Metal Hydroxide	Proprietary		2.253	mg	20000	6288
				supplier	CORE	Copper (Cu)	7440-50-8		47.316	mg	420000	132053
				supplier	SOLDERMASK (AUS320)	Solvent naptha(petroleum),heavy aromatic	64742-94-5		6.196	mg	55000	17293
				supplier	SOLDERMASK (AUS320)	Napthalene	91-20-3		0.653	mg	5800	1824
				supplier	SOLDERMASK (AUS320)	Phosphinoxide derivative	Proprietary		0.225	mg	2000	629
				supplier	SOLDERMASK (AUS320)	Talc containing no asbestiform fibers	14807-96-6		1.690	mg	15000	4716
				supplier	SOLDERMASK (AUS320)	Barium sulfate	7727-43-7		2.816	mg	25000	7860
				supplier	SOLDERMASK (AUS320)	Dipropylene glycol monomethyl ether	34590-94-8		1.690	mg	15000	4716
				supplier	CU PLATING	Copper (Cu)	7440-50-8		4.056	mg	36000	11319
				supplier	NI PLATING	Nickel (Ni)	7440-02-0		0.563	mg	5000	1572
				supplier	AU PLATING	Gold (Au)	7440-57-5		0.135	mg	1200	377
DIE ATTACH (2300)	M-011 Other inorganic materials	2.057	mg	supplier	GLUE	Silver (Ag)	7440-22-4		1.858	mg	903000	5184
				supplier	GLUE	Bismaleimide monomer	Proprietary		0.197	mg	96000	551
				supplier	GLUE	Silane	Proprietary		0.002	mg	1000	6
BONDING WIRE (MKE 4N)	M-011 Other inorganic materials	4.418	mg	supplier	BONDING WIRE	Gold (Au)	7440-57-5		4.418	mg	1000000	12329
SOLDERBALL (Sn98.5Ag0.1Cu0.5)	M-011 Other inorganic materials	35.598	mg	supplier	SOLDERBALL	Tin (Sn)	7440-31-5		35.064	mg	985000	97858
				supplier	SOLDERBALL	Silver (Ag)	7440-22-4		0.356	mg	10000	993
				supplier	SOLDERBALL	Copper (Cu)	7440-50-8		0.178		5000	497
ENCAPSULATION (GE-100LFCS)	M-011 Other inorganic materials	173.350	mg	supplier	MOLDING COMPOUND	Silica fused (SiO2)	60676-86-0		154.425	mg	900000	430978
				supplier	MOLDING COMPOUND	Epoxy resin	Proprietary		8.517	mg	45000	23769
				supplier	MOLDING COMPOUND	Phenol resin	Proprietary		7.570	mg	40000	21128
				supplier	MOLDING COMPOUND	Metal Hydroxide	Proprietary		1.893	mg	10000	5282
				supplier	MOLDING COMPOUND	Carbon black	1333-86-4		0.946	mg	5000	2641